

Schottky Rectifiers

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter		Value			
		1635	1645	1650	1660	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	35	45	50	60	V
I _{F(AV)}	Average Rectified Forward Current .375 " lead length @ $T_A = 125^{\circ}C$	16			А	
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	150			А	
T _{stg}	Storage Temperature Range		-65 to +175			°C
TJ	Operating Junction Temperature		-65 to +150			°C

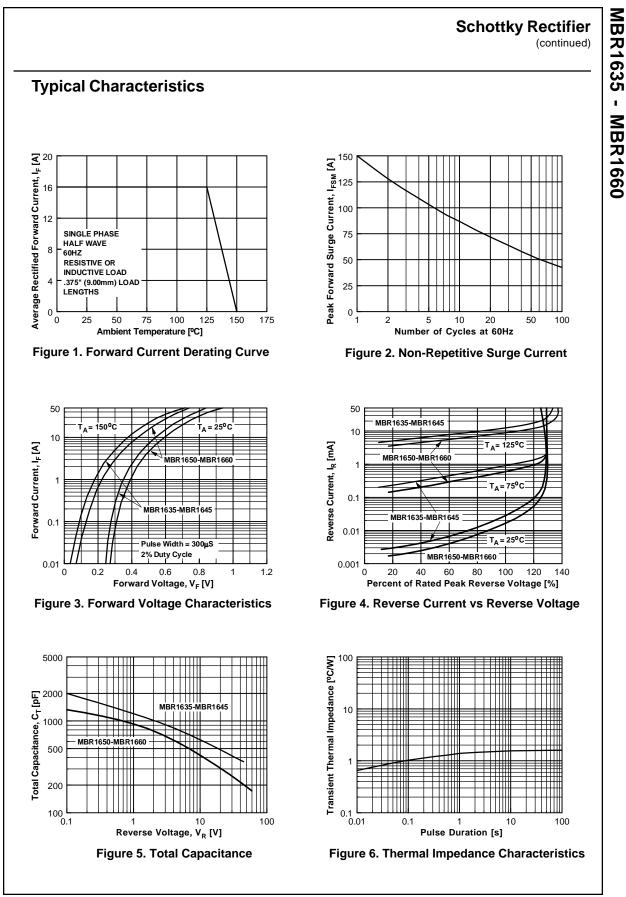
*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Power Dissipation	2.0	W
R_{\thetaJA}	Thermal Resistance, Junction to Ambient	60	°C/W
$R_{ extsf{ hetaJL}}$	Thermal Resistance, Junction to Lead	1.5	°C/W

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Device				Units
		1635	1645	1650	1660	1
V_{F}	Forward Voltage $I_{F=}$ 16 A, T_{C} = 25°C $I_{F=}$ 16 A, T_{C} = 125°C	0.63 0.57		0.75 0.65		V V
I _R	Reverse Current @ rated $V_R T_A = 25^{\circ}C$ $T_A = 125^{\circ}C$	0.2 40		1.0 50		mA mA
I _{RRM}	Peak Repetitive Reverse Surge Current 2.0 us Pulse Width, f = 1.0 KHz	1.0		0.5		А



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MBR1635 - MBR1660 Rev. C

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